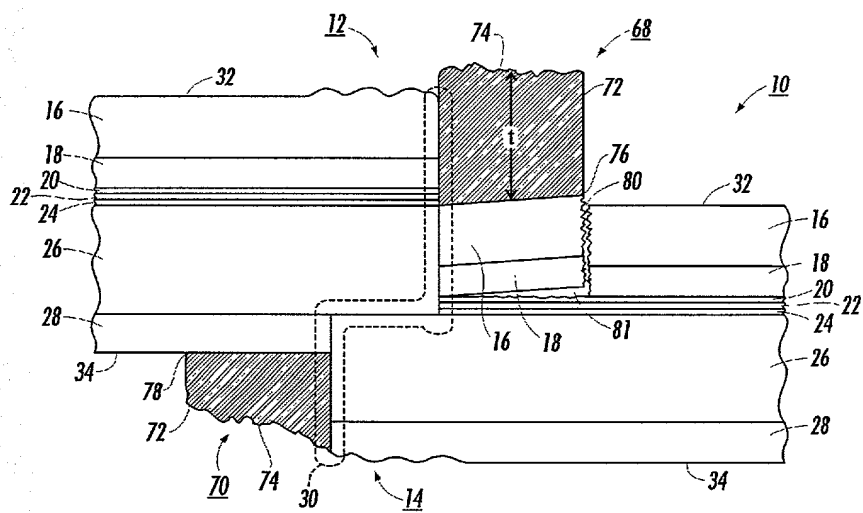
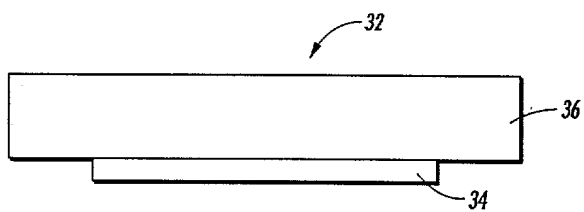


**FIG. 1**





**FIG. 3**



**FIG. 4**

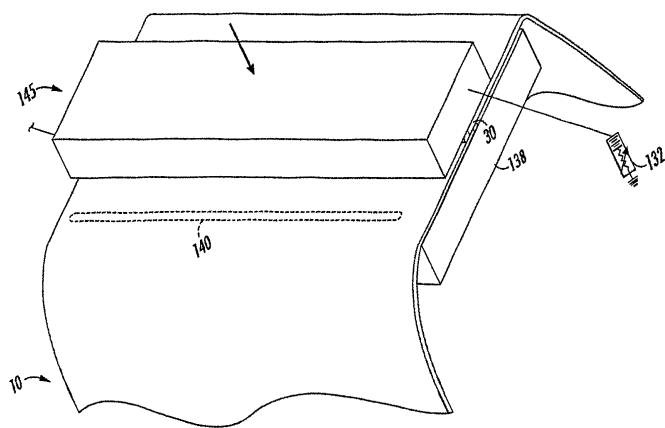


FIG. 5

FIG. 5

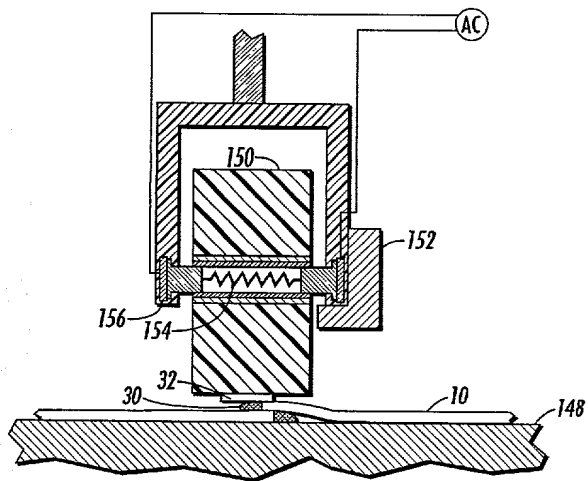


FIG. 6

FIG. 6 is a cross-sectional view of a device assembly. A central block 150 is mounted on a base 10. A spring 154 is positioned between block 150 and a lower block 156. A component 152 is connected to block 150 and a terminal AC. A layer 32 is on the base 10, and a layer 148 is on top of block 150. A label 30 points to the base area.

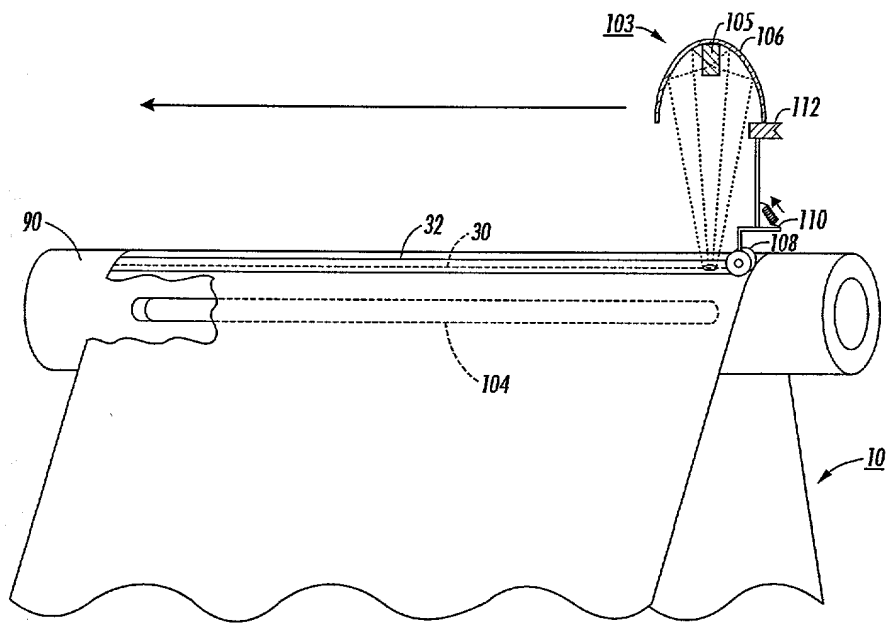
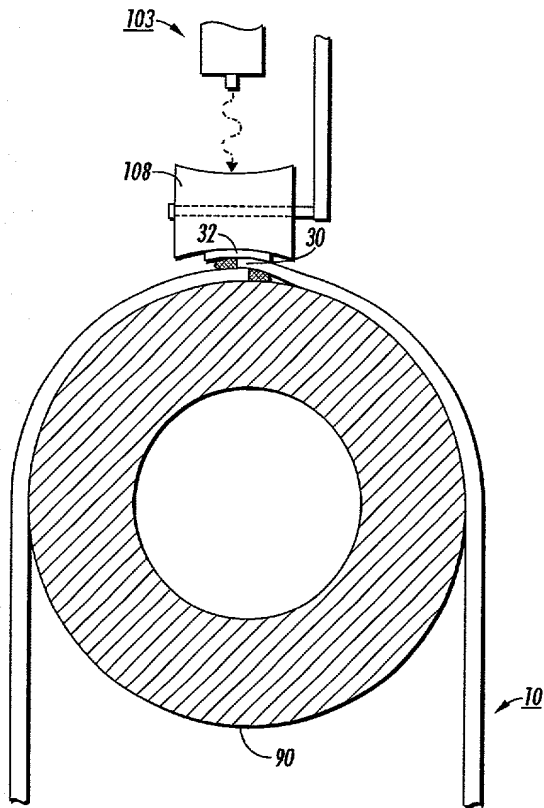


FIG. 7



**FIG. 8**



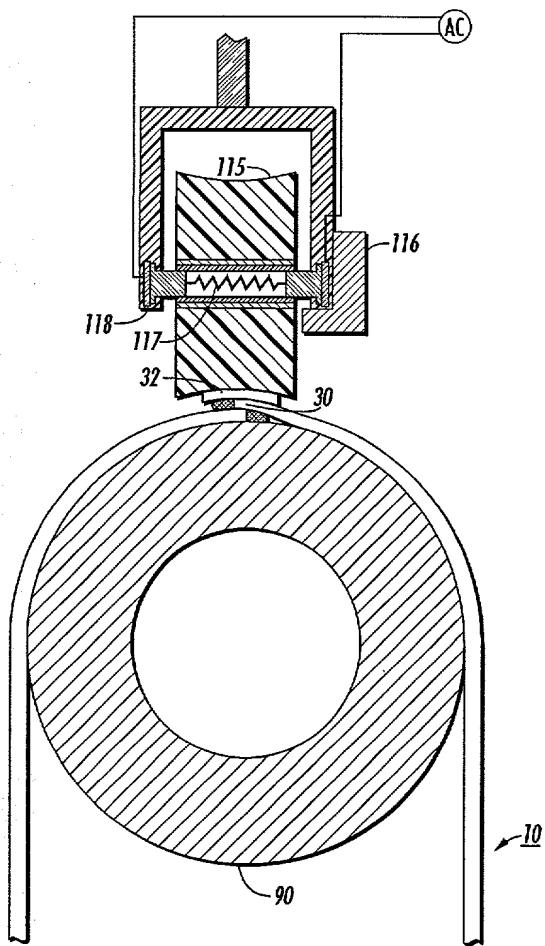


FIG. 9